



1.0A HIGH VOLTAGE SCHOTTKY BARRIER RECTIFIER POWERDI® 123

Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- Lead Free Finish, RoHS Compliant (Note 1)
- "Green" Molding Compound (No Br, Sb)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: POWERDI[®]123
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (83)
- Weight: 0.01 grams (approximate)



Top View

Ordering Information (Note 2)

Part Number	Case	Packaging
DFLS1100-7	POWERDI [®] 123	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes
- 2. For packaging details, go to our website at http://www.diodes.com.

Marking Information



F09 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: T = 2006) M = Month (ex: 9 = September)

Date Code Key

Year	2004	20	005	2006	2007	20	08	2009	2010	20)11	2012
Code	R	,	S	Т	U	\	/	W	X	·	Y	Z
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100	V
RMS Reverse Voltage	V _{R(RMS)}	71	V
Forward current rms ($T_C = 160^{\circ}C$, $D = 0.5$)	I _{F(RMS)}	2	A
Average Forward Current	I _{F(AV)}	1.0	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	50	А
Repetitive peak reverse current tp = 2µs, f = I kHz square	I _{RRM}	1.0	А
Repetitive Peak Avalanche Power tp = 1 µs, TJ = 25°C	P _{ARM}	1500	W
Non-repetitive peak reverse current tp = 100µs square	I _{RSM}	1.0	A
Critical rate of rise of reverse voltage (rated V _R , T _J = 25 °C)	dV/dt	10000	V/µs

Thermal Characteristics

Characteristic	Symbol	Тур	Max	Unit
Thermal Resistance Junction to Soldering (Note 3)	$R_{ hetaJS}$	_	7	00044
Thermal Resistance Junction to Ambient (Note 4) T _A = 25°C	$R_{ hetaJA}$	125	_	°C/W
Thermal Resistance Junction to Case (Note 4) T _A = 25°C	$R_{ heta JC}$	21	_	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to	+175	°C

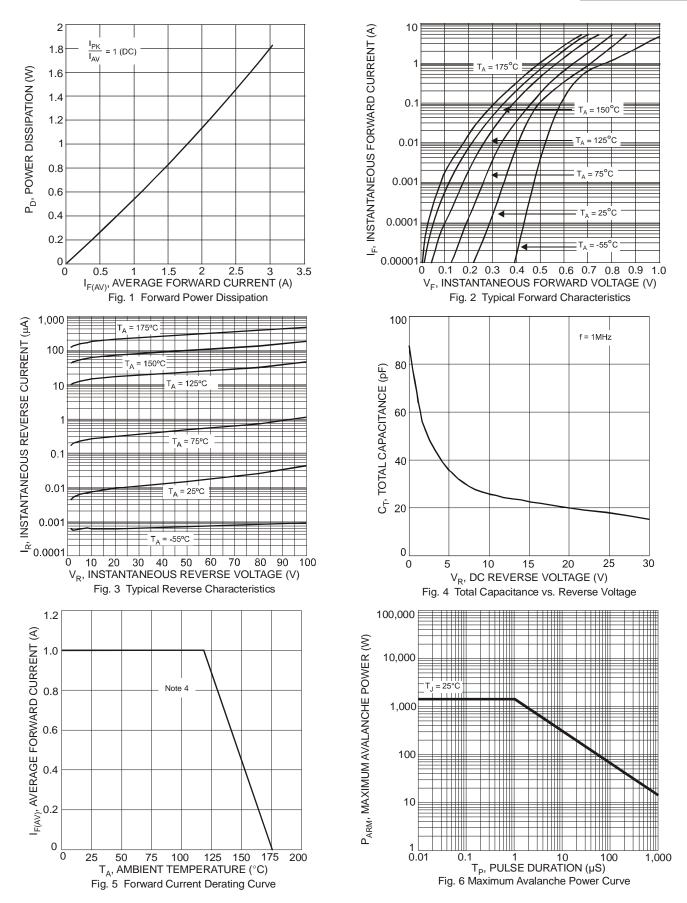
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	100	_	_	V	$I_R = 1\mu A$
		_	_	0.77		$I_F = 1.0A, T_A = 25^{\circ}C$
Forward Voltage	V	0.58	0.62	V	I _F = 1.0A, T _A = 125°C	
Forward voltage	V _F		_	0.86	ľ	$I_F = 2.0A, T_A = 25^{\circ}C$
			0.65	0.7		I _F = 2.0A, T _A = 125°C
Lookaga Current (Nota E)		_	_	1	μΑ	V _R = 100V, T _A = 25°C
Leakage Current (Note 5)	I _R	_	0.2	0.5	mA	$V_R = 100V, T_A = 125^{\circ}C$
Total Capacitance	C _T	_	36	_	pF	$V_R = 5V_{DC}, f = 1MHz$

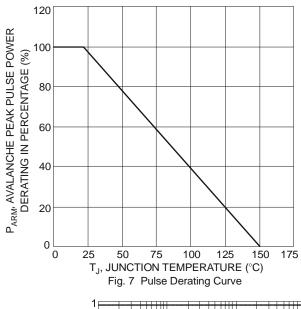
Notes:

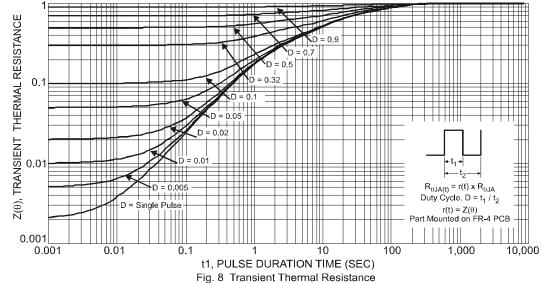
- 3. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 4. Part mounted on FR-4 board with 2 oz., minimum recommended copper pad layout, which can be found on our website at http://www.diodes.com.
- 5. Short duration pulse test used to minimize self-heating effect.





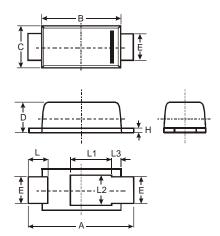






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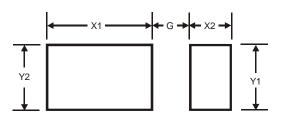
Package Outline Dimensions



POWERDI®123							
Dim	Min Max		Тур				
Α	3.50	3.90	3.70				
В	2.60	3.00	2.80				
O	1.63	1.93	1.78				
ם	0.93	1.00	0.98				
Е	0.85	1.25	1.00				
Н	0.15	0.25	0.20				
L	0.40	0.50	0.45				
L1	-	-	1.35				
L2	-	1	1.10				
L3	-	1	0.20				
All Dimensions in mm							



Suggested Pad Layout



Dimensions	Value (in mm)			
G	1.0			
X1	2.2			
X2	0.9			
Y1	1.4			
Y2	1.4			

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